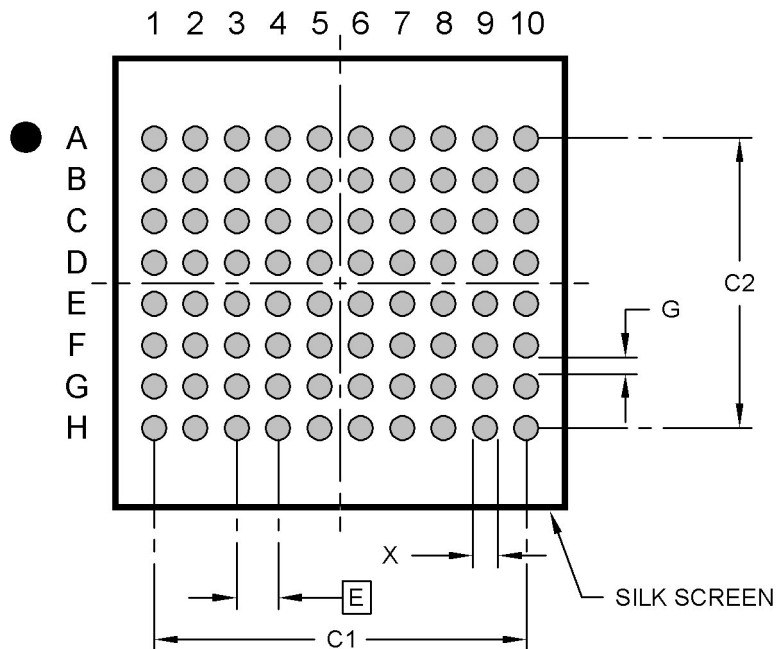


80-Ball Wafer Level Chip Scale Package (6SW) - 3.513x3.593x0.446 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.35 BSC		
Contact Pad Spacing	C1		3.15	
Contact Pad Spacing	C2		2.45	
Contact Pad Diameter (X80)	X			0.20
Contact Pad to Contact Pad	G	0.14		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process